

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	85	V
Peak Repetitive Reverse Voltage	V <sub>R RM</sub>	80	V
Working Peak Reverse Voltage	V <sub>R WM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	57	V
Forward Continuous Current	I <sub>FM</sub>	300	mA
Average Rectified Output Current	I <sub>O</sub>	100	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs	I <sub>FSM</sub>	2.0	A

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	350	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	357	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	80	—	—	V	I <sub>R</sub> = 100μA
Forward Voltage	V <sub>F</sub>	—	0.62 0.74 0.94	0.7 0.82 1.20	V	I <sub>F</sub> = 1.0mA I <sub>F</sub> = 10mA I <sub>F</sub> = 100mA
Leakage Current (Note 6)	I <sub>R</sub>	—	5	10.0	nA μA μA	V <sub>R</sub> = 5V V <sub>R</sub> = 30V V <sub>R</sub> = 80V
Total Capacitance	C <sub>T</sub>	—	0.5	2.5	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	—	4.0 4.0	ns ns	I <sub>F</sub> = 10mA, V <sub>R</sub> = 6V I <sub>F</sub> = I <sub>R</sub> = 10mA, t <sub>rr</sub> = 0.1 × I <sub>R</sub> , R <sub>L</sub> = 100Ω

Notes: 5. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.  
 6. Short duration pulse test used to minimize self-heating effect.

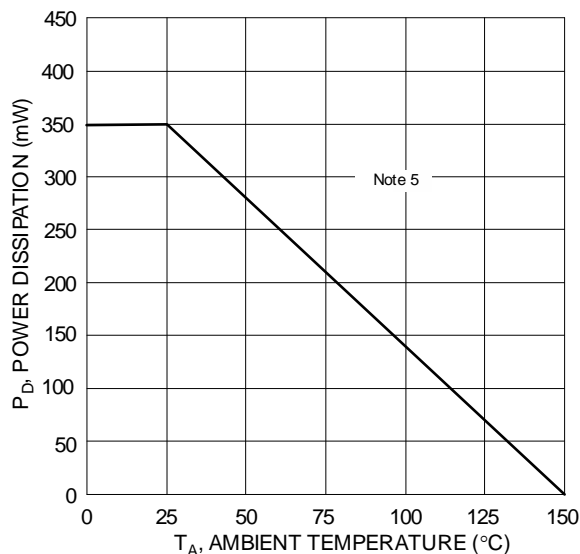


Figure 1 Power Derating Curve, Total Package

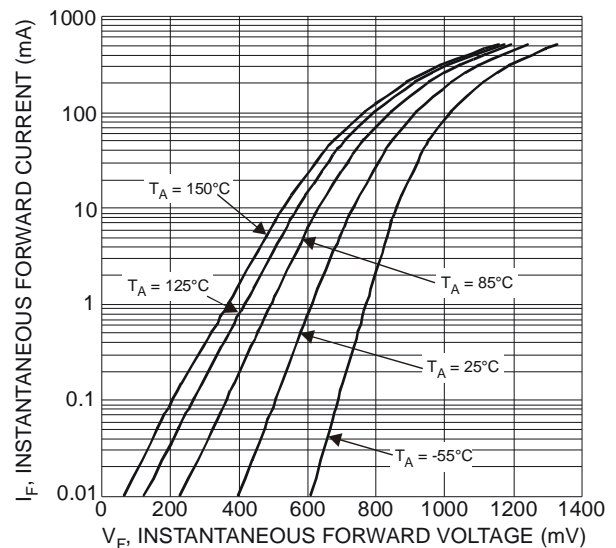
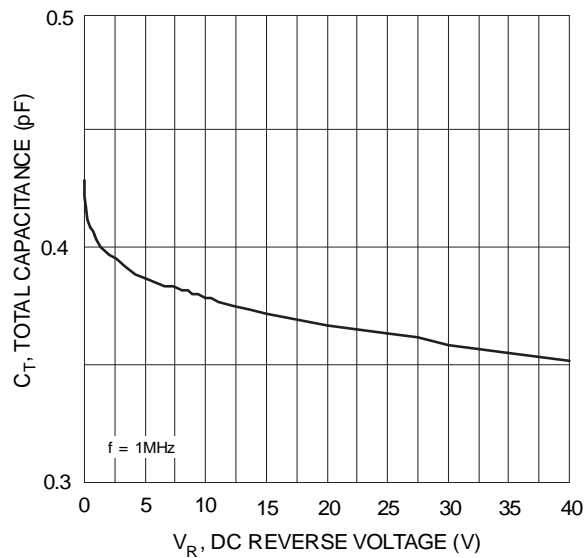
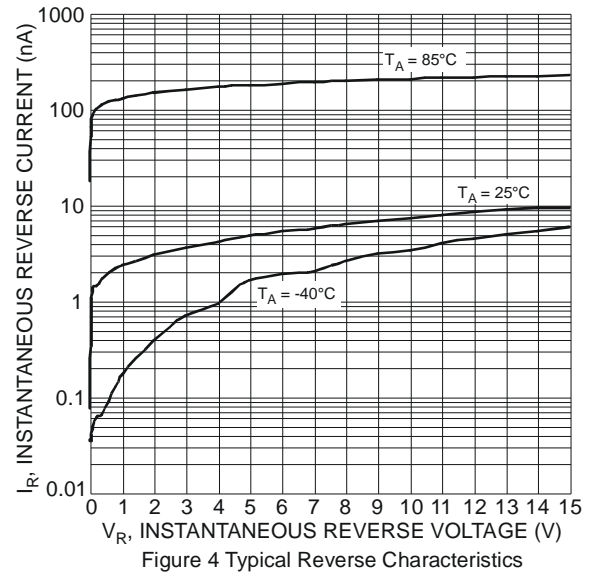
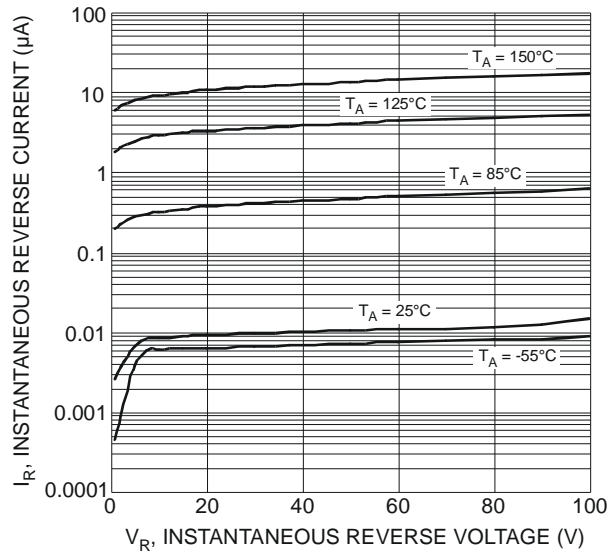
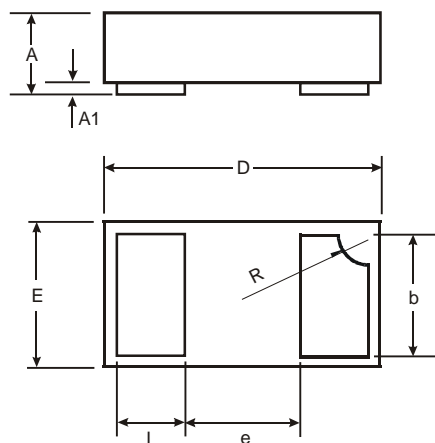


Figure 2 Typical Forward Characteristics



## Package Outline Dimensions

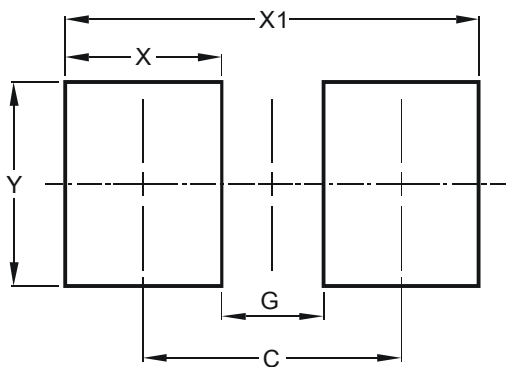
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X2-DFN1006-2			
Dim	Min	Max	Typ
A	0.34	0.4	0.37
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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